



Competence in Silicon

Nanotechnology meets temperature-sensitive devices

CiS Research Insititut for micorsensor systems

From silicon-die to microsensor systems





Overview

- company CiS
- motivation
- overview about complete sensor
- function and design of lightning unit
- joining technology
- summary



Some Facts about CiS



Non-profit research institution under private law (GmbH)

120

Founded in 1993

Total output 2017

- Public research projects
- Industrial contract research and manufacturing
- No basic financing

Employees 2017

• R&D 91

Skilled workers, assistants

Planes / Areas

•	Clean room class	10	100 m ²
•	Clean room class	100	500 m ²
•	Clean room class	10.000	1.000 m ²
•	Air-conditioned laboratories		1 000 m ²

15,0 Mio. €

50 %

50 %



Technological competencies





- Simulation and Design
- Wafer Technology
- Assembly and Packaging (AVT)
- Metrology / Measurement technology and analytics

Our Mission



...is to support our industrial customers by developing innovative solutions in micro-system technologies

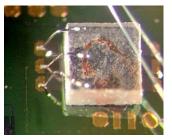
Analysing of the technical potential of the latest scientific results

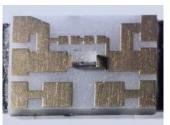
Developing prototypes for the customer with the focus on producibility, reliability and stability

Prototyping and transfer





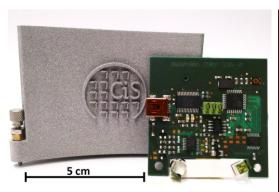


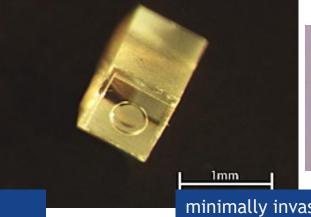




2. Motivation





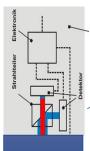




Coating-thickness-gauge Simple sensor system Requirements: Two wavelength 850nm and 670nm Polarized and collimated light source minimally invasive High volume market High light intensity Polarized light Miniaturized unit Mass production Laser light VCSEL

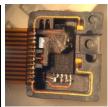
3. Complete Sensor System





Detector Beamsplitter in MID Case

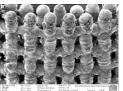


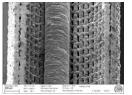




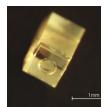
Measurement Chamber Metal-Cannula 1,2mm Diameter 25 mm lenght

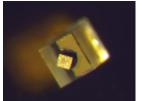






Source VCSEL 670nm



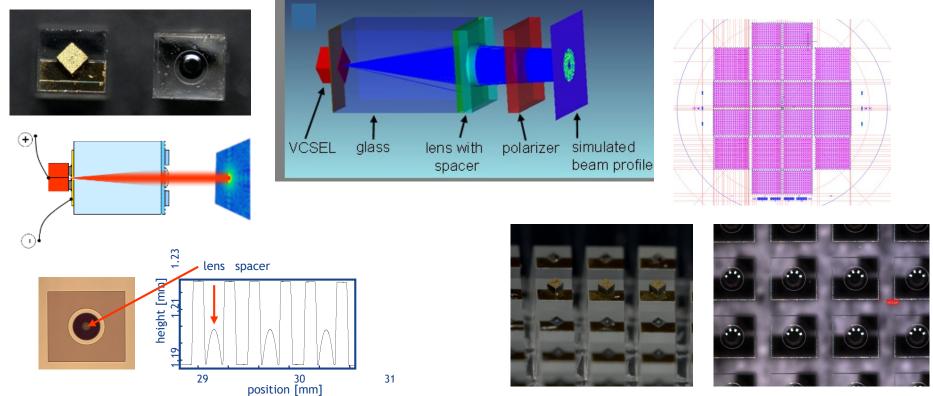




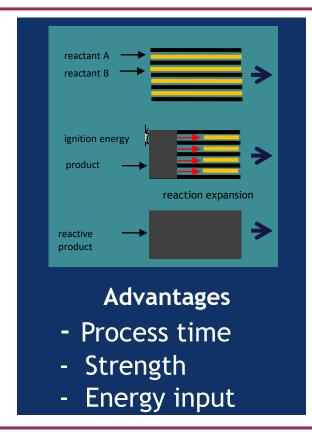


4. function and design of the lightning unit



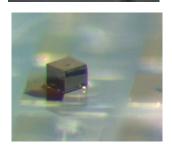


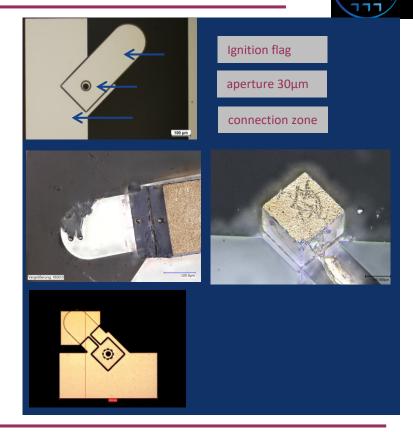
5.0 joining technology - reactive Bonding





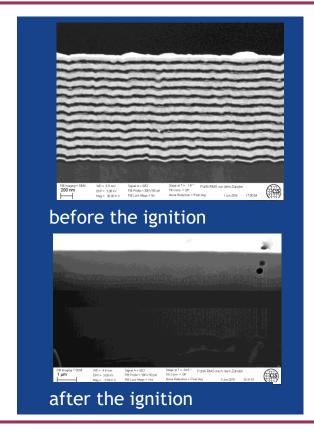






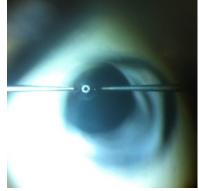
5.1. joining technology - reactive Bonding

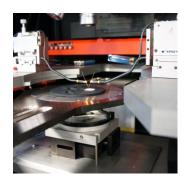


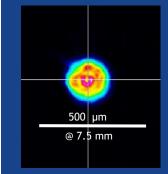


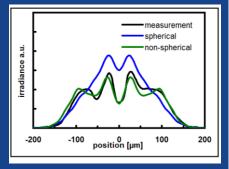












6.0 Summary

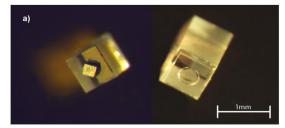


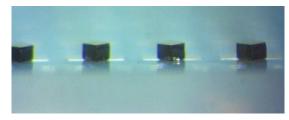
What did we do:

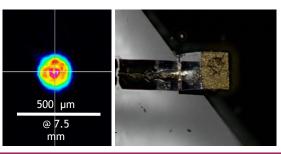
- -introduction of reactive Bonding technology
- -Consistent miniaturizing
- -Complete wafer-level-assembly
- -Full automatic pick&place process
- -Full automatic function-controlling

Which ultimately came out:

- -solid miniaturized and stable laser light unit
- -Light beam spot 300µm by distance 25mm
- -low cost high-volume production







Thank you for your attention!

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